

74LVC573A-Q100

Octal D-type transparent latch with 5 V tolerant inputs/outputs; 3-state

Rev. 1 — 29 January 2013

Product data sheet

1. General description

The 74LVC573A-Q100 consists of eight D-type transparent latches, featuring separate D-type inputs for each latch and 3-state true outputs for bus-oriented applications. A Latch Enable (LE) input and an Output Enable (\overline{OE}) input are common to all internal latches.

When LE is HIGH, data at the Dn inputs enters the latches. In this condition, the latches are transparent, that is, a latch output changes each time its corresponding D-input changes. When LE is LOW, the latches store the information that was present at the D-inputs one set-up time preceding the HIGH-to-LOW transition of LE.

When \overline{OE} is LOW, the contents of the eight latches are available at the outputs. When \overline{OE} is HIGH, the outputs go to the high impedance OFF-state. Operation of the \overline{OE} input does not affect the state of the latches.

Inputs can be driven from either 3.3 V or 5 V devices. When disabled, up to 5.5 V can be applied to the outputs. These features allow the use of these devices as translators in mixed 3.3 V or 5 V applications.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- 5 V tolerant inputs/outputs, for interfacing with 5 V logic
- Supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- High-impedance when $V_{CC} = 0\text{ V}$
- Flow-through pinout architecture
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pF}$, $R = 0\text{ }\Omega$)



3. Ordering information

Table 1. Ordering information

| Type number | Package | | | Version |
|------------------|-------------------|----------|--------------------------------------------------------------------------------------------------------------------------------|----------|
| | Temperature range | Name | Description | |
| 74LVC573AD-Q100 | -40 °C to +125 °C | SO20 | plastic small outline package; 20 leads; body width 7.5 mm | SOT163-1 |
| 74LVC573APW-Q100 | -40 °C to +125 °C | TSSOP20 | plastic thin shrink small outline package; 20 leads; body width 4.4 mm | SOT360-1 |
| 74LVC573ABQ-Q100 | -40 °C to +125 °C | DHVQFN20 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm | SOT764-1 |

4. Functional diagram

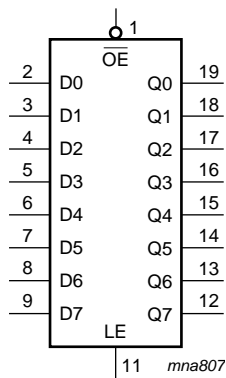


Fig 1. Logic symbol

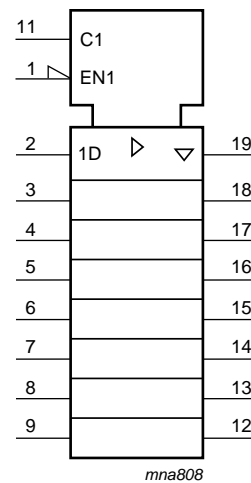


Fig 2. IEC logic symbol

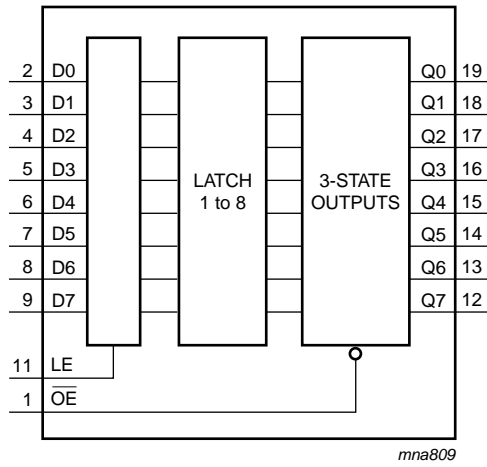


Fig 3. Functional diagram

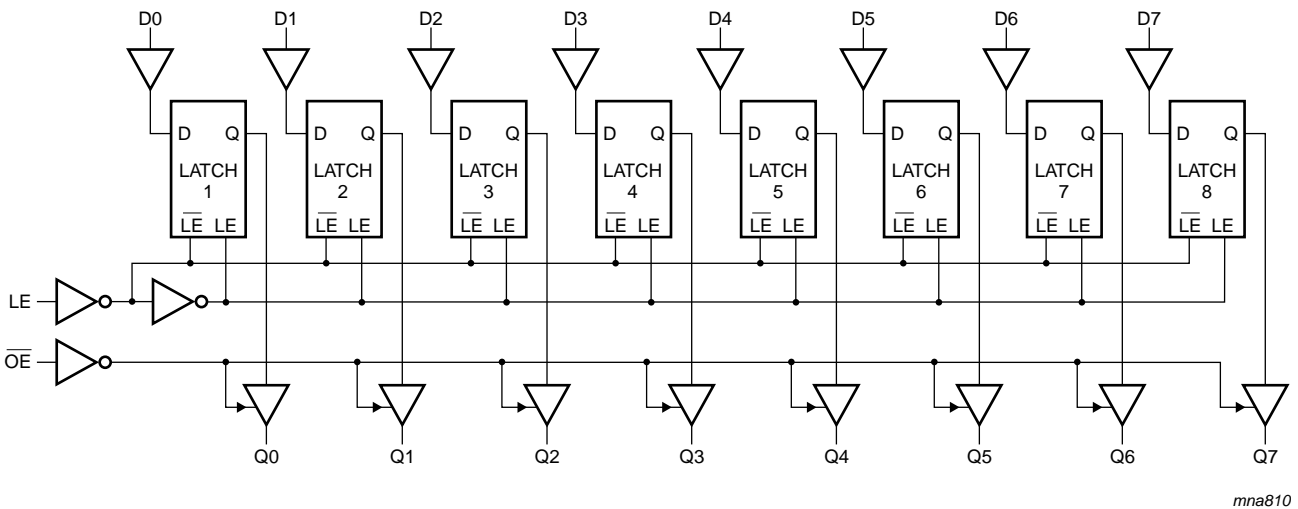
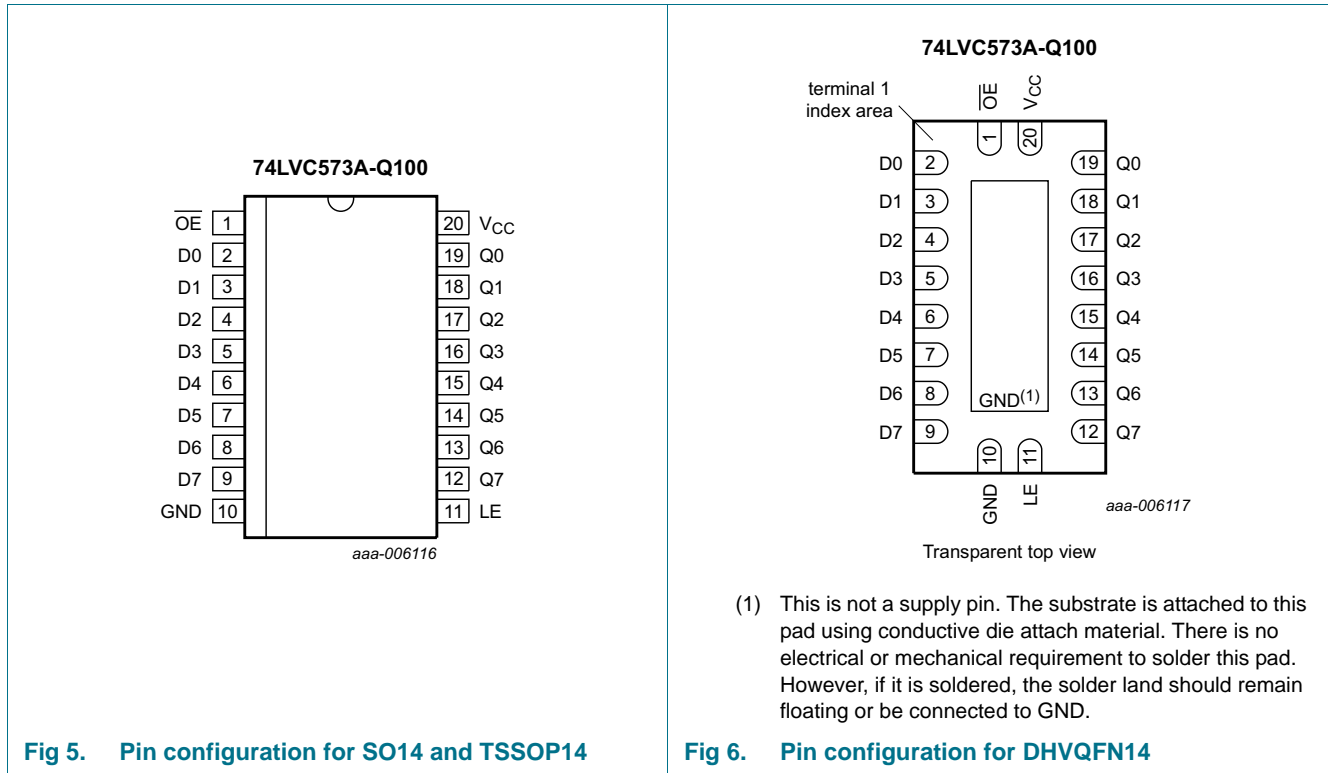


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|-----------------|--------------------------------|----------------------------------|
| \overline{OE} | 1 | output enable input (active LOW) |
| LE | 11 | latch enable input (active HIGH) |
| D[0:7] | 2, 3, 4, 5, 6, 7, 8, 9 | data input |
| Q[0:7] | 19, 18, 17, 16, 15, 14, 13, 12 | data output |
| GND | 10 | ground (0 V) |
| V_{CC} | 20 | supply voltage |

6. Functional description

Table 3. Functional table^[1]

| Operating modes | Input | | | Internal latch | Output Qn |
|------------------------------------------------|------------------------|----|----|----------------|--------------|
| | $\overline{\text{OE}}$ | LE | Dn | | |
| Enable and read register (transparent mode) | L | H | L | L | L |
| | L | H | H | H | H |
| Latch and read register | L | L | l | L | L |
| | L | L | h | H | H |
| Latch register and disable outputs | H | L | l | L | Z |
| | H | L | h | H | Z |

- [1] H = HIGH voltage level
 h = HIGH voltage level one set-up time prior to the HIGH-to-LOW LE transition
 L = LOW voltage level
 l = LOW voltage level one set-up time prior to the HIGH-to-LOW LE transition
 Z = high-impedance OFF-state

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|------------------------------------------------|---------------------|----------------|------|
| V_{CC} | supply voltage | | -0.5 | +6.5 | V |
| I_{IK} | input clamping current | $V_I < 0$ | -50 | - | mA |
| V_I | input voltage | | ^[1] -0.5 | +6.5 | V |
| I_{OK} | output clamping current | $V_O > V_{CC}$ or $V_O < 0$ | - | ± 50 | mA |
| V_O | output voltage | | ^[2] -0.5 | $V_{CC} + 0.5$ | V |
| I_O | output current | $V_O = 0 \text{ V to } V_{CC}$ | - | ± 50 | mA |
| I_{CC} | supply current | | - | 100 | mA |
| I_{GND} | ground current | | -100 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | $T_{amb} = -40 \text{ °C to } +125 \text{ °C}$ | ^[3] - | 500 | mW |

- [1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.
 [2] The output voltage ratings may be exceeded if the output current ratings are observed.
 [3] For SO20 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
 For TSSOP20 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.
 For DHVQFN20 packages: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|-------------------------------------|-----------------------------------|------|-----|-----------------|------|
| V _{CC} | supply voltage | | 1.65 | - | 3.6 | V |
| | | functional | 1.2 | - | - | V |
| V _I | input voltage | | 0 | - | 5.5 | V |
| V _O | output voltage | output HIGH- or LOW-state | 0 | - | V _{CC} | V |
| | | output 3-state | 0 | - | 5.5 | V |
| T _{amb} | ambient temperature | in free air | -40 | - | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 1.65 V to 2.7 V | 0 | - | 20 | ns/V |
| | | V _{CC} = 2.7 V to 3.6 V | 0 | - | 10 | ns/V |

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|-------------------------------------------------------------|------------------------|--------------------|------------------------|------------------------|------------------------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 1.2 V | 1.08 | - | - | 1.08 | - | V |
| | | V _{CC} = 1.65 V to 1.95 V | 0.65 × V _{CC} | - | - | 0.65 × V _{CC} | - | V |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | - | - | 1.7 | - | V |
| | | V _{CC} = 2.7 V to 3.6 V | 2.0 | - | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 1.2 V | - | - | 0.12 | - | 0.12 | V |
| | | V _{CC} = 1.65 V to 1.95 V | - | - | 0.35 × V _{CC} | - | 0.35 × V _{CC} | V |
| | | V _{CC} = 2.3 V to 2.7 V | - | - | 0.7 | - | 0.7 | V |
| | | V _{CC} = 2.7 V to 3.6 V | - | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | |
| | | I _O = -100 μA; V _{CC} = 1.65 V to 3.6 V | V _{CC} - 0.2 | - | - | V _{CC} - 0.3 | - | V |
| | | I _O = -4 mA; V _{CC} = 1.65 V | 1.2 | - | - | 1.05 | - | V |
| | | I _O = -8 mA; V _{CC} = 2.3 V | 1.8 | - | - | 1.65 | - | V |
| | | I _O = -12 mA; V _{CC} = 2.7 V | 2.2 | - | - | 2.05 | - | V |
| | | I _O = -18 mA; V _{CC} = 3.0 V | 2.4 | - | - | 2.25 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | |
| | | I _O = 100 μA; V _{CC} = 1.65 V to 3.6 V | - | - | 0.2 | - | 0.3 | V |
| | | I _O = 4 mA; V _{CC} = 1.65 V | - | - | 0.45 | - | 0.65 | V |
| | | I _O = 8 mA; V _{CC} = 2.3 V | - | - | 0.6 | - | 0.8 | V |
| | | I _O = 12 mA; V _{CC} = 2.7 V | - | - | 0.4 | - | 0.6 | V |
| | | I _O = 24 mA; V _{CC} = 3.0 V | - | - | 0.55 | - | 0.8 | V |
| I _I | input leakage current | V _{CC} = 3.6 V; V _I = 5.5 V or GND | - | ±0.1 | ±5 | - | ±20 | μA |

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|-----------------------------------------------------------------------------------------------------------------|------------------|--------------------|-----|-------------------|------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _{CC} = 3.6 V; V _O = 5.5 V or GND; | - | 0.1 | ±5 | - | ±20 | µA |
| I _{OFF} | power-off leakage current | V _{CC} = 0 V; V _I or V _O = 5.5 V | - | 0.1 | ±10 | - | ±20 | µA |
| I _{CC} | supply current | V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A | - | 0.1 | 10 | - | 40 | µA |
| ΔI _{CC} | additional supply current | per input pin; V _{CC} = 2.7 V to 3.6 V; V _I = V _{CC} - 0.6 V; I _O = 0 A | - | 5 | 500 | - | 5000 | µA |
| C _I | input capacitance | V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC} | - | 5.0 | - | - | - | pF |

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 11](#).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|----------------------------------|-------------------|-------------------------------------------------------|------------------|--------------------|------|-------------------|------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| t _{pd} | propagation delay | Dn to Qn; see Figure 7 ^[2] | | | | | | |
| | | V _{CC} = 1.2 V | - | 16.0 | - | - | - | ns |
| | | V _{CC} = 1.65 V to 1.95 V | 2.1 | 7.8 | 16.3 | 2.1 | 18.8 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 1.5 | 4.1 | 8.0 | 1.5 | 9.2 | ns |
| | | V _{CC} = 2.7 V | 1.5 | 4.1 | 7.2 | 1.5 | 9.0 | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 1.5 | 3.4 | 6.2 | 1.5 | 8.0 | ns |
| | | LE to Qn; see Figure 8 ^[2] | | | | | | |
| | | V _{CC} = 1.2 V | - | 16.0 | - | - | - | ns |
| | | V _{CC} = 1.65 V to 1.95 V | 2.0 | 7.7 | 16.0 | 2.0 | 18.4 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 1.5 | 4.1 | 7.8 | 1.5 | 9.1 | ns |
| V _{CC} = 2.7 V | 1.5 | 3.7 | 7.5 | 1.5 | 9.5 | ns | | |
| V _{CC} = 3.0 V to 3.6 V | 1.5 | 3.4 | 6.5 | 1.5 | 8.5 | ns | | |
| t _{en} | enable time | OE to Qn; see Figure 9 ^[2] | | | | | | |
| | | V _{CC} = 1.2 V | - | 18.0 | - | - | - | ns |
| | | V _{CC} = 1.65 V to 1.95 V | 1.7 | 7.5 | 17.5 | 1.7 | 20.2 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 1.5 | 4.2 | 9.2 | 1.5 | 10.6 | ns |
| | | V _{CC} = 2.7 V | 1.5 | 4.2 | 8.5 | 1.5 | 11.0 | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 1.5 | 3.4 | 7.5 | 1.5 | 9.5 | ns |

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 11](#).

| Symbol | Parameter | Conditions | -40 °C to +85 °C | | | -40 °C to +125 °C | | Unit |
|--------------------|-------------------------------|-------------------------------------------------------------------|------------------|--------------------|------|-------------------|------|------|
| | | | Min | Typ ^[1] | Max | Min | Max | |
| t _{dis} | disable time | OE to Qn; see Figure 9 ^[2] | | | | | | |
| | | V _{CC} = 1.2 V | - | 8.0 | - | - | - | ns |
| | | V _{CC} = 1.65 V to 1.95 V | 1.0 | 3.3 | 10.1 | 1.0 | 11.6 | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 0.3 | 1.8 | 5.7 | 0.3 | 6.6 | ns |
| | | V _{CC} = 2.7 V | 1.5 | 3.0 | 6.5 | 1.5 | 8.5 | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 1.5 | 2.5 | 6.0 | 1.5 | 7.5 | ns |
| t _w | pulse width | LE HIGH; see Figure 8 | | | | | | |
| | | V _{CC} = 1.65 V to 1.95 V | 5.0 | - | - | 5.0 | - | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 4.0 | - | - | 4.0 | - | ns |
| | | V _{CC} = 2.7 V | 3.2 | - | - | 3.2 | - | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 3.2 | 1.6 | - | 3.2 | - | ns |
| t _{su} | set-up time | nD to nCP; see Figure 10 | | | | | | |
| | | V _{CC} = 1.65 V to 1.95 V | 4.0 | - | - | 4.0 | - | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 2.5 | - | - | 2.5 | - | ns |
| | | V _{CC} = 2.7 V | 1.7 | - | - | 1.7 | - | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 1.7 | - | - | 1.7 | - | ns |
| t _h | hold time | Dn to LE; see Figure 10 | | | | | | |
| | | V _{CC} = 1.65 V to 1.95 V | 3.0 | - | - | 3.0 | - | ns |
| | | V _{CC} = 2.3 V to 2.7 V | 1.9 | - | - | 1.9 | - | ns |
| | | V _{CC} = 2.7 V | 1.5 | - | - | 1.5 | - | ns |
| | | V _{CC} = 3.0 V to 3.6 V | 1.4 | - | - | 1.4 | - | ns |
| t _{sk(o)} | output skew time | V _{CC} = 3.0 V to 3.6 V ^[3] | - | - | 1.0 | - | 1.5 | ns |
| C _{PD} | power dissipation capacitance | per latch; V _I = GND to V _{CC} ^[4] | | | | | | |
| | | V _{CC} = 1.65 V to 1.95 V | - | 7.1 | - | - | - | pF |
| | | V _{CC} = 2.3 V to 2.7 V | - | 10.3 | - | - | - | pF |
| | | V _{CC} = 3.0 V to 3.6 V | - | 13.2 | - | - | - | pF |

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

t_{en} is the same as t_{PZL} and t_{PZH}.

t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

P_D = C_{PD} × V_{CC}² × f_i × N + Σ(C_L × V_{CC}² × f_o) where:

f_i = input frequency in MHz; f_o = output frequency in MHz

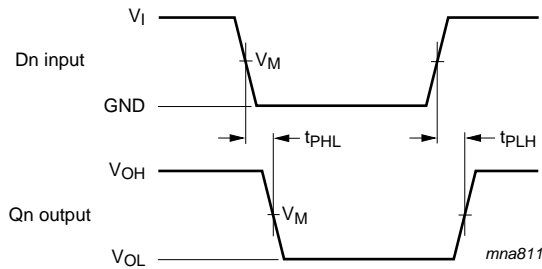
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

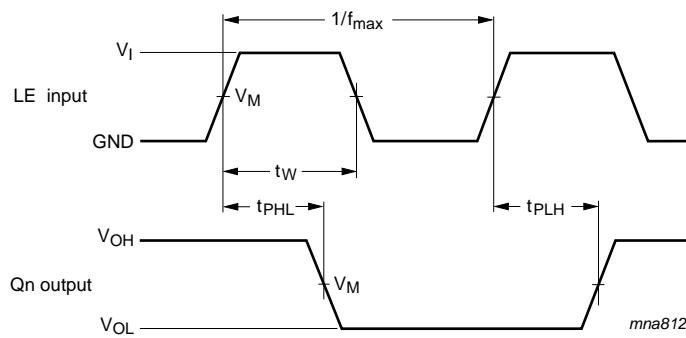
Σ(C_L × V_{CC}² × f_o) = sum of the outputs

11. AC waveforms



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 7. Input (Dn) to output (Qn) propagation delays



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 8. Latch Enable input (LE) pulse width, the latch enable input to output (Qn) propagation delays

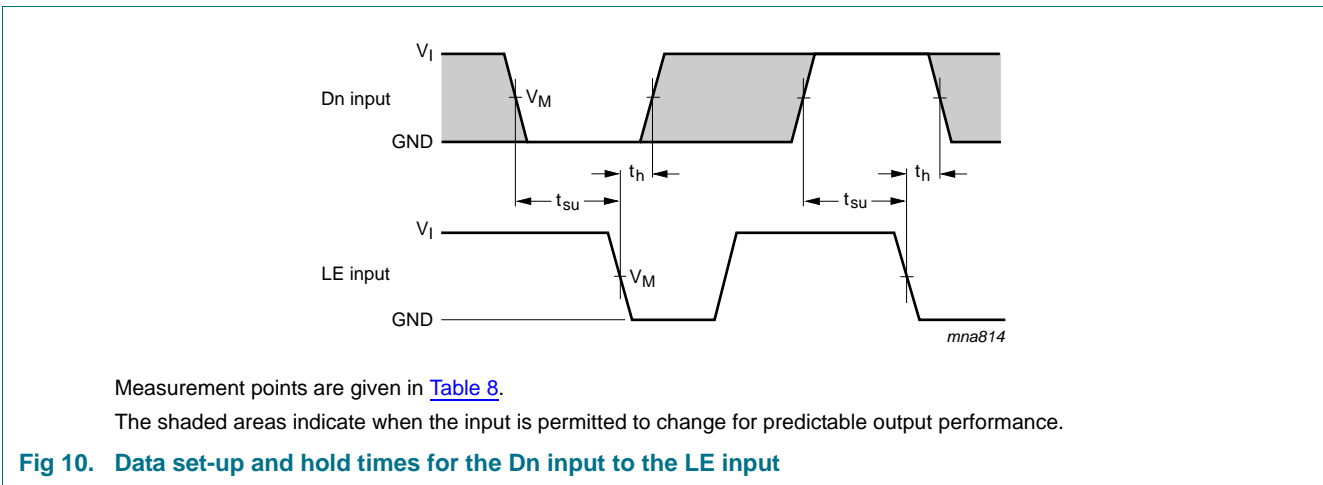
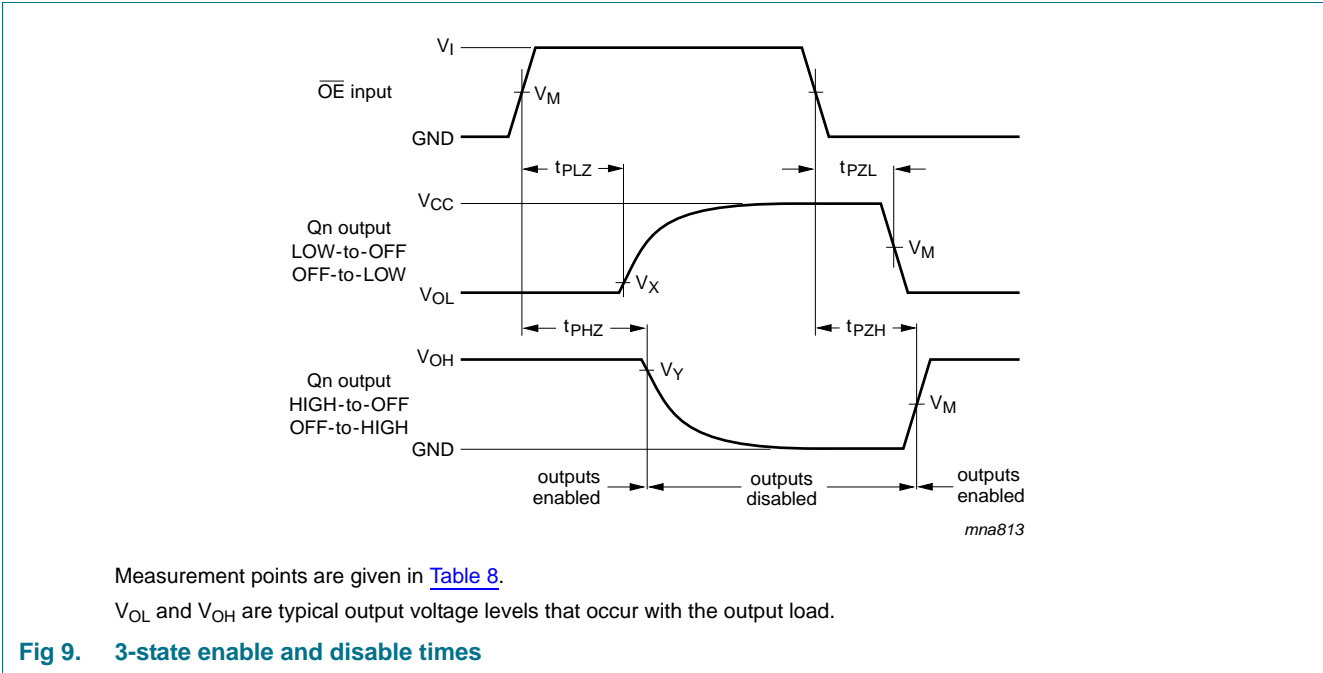
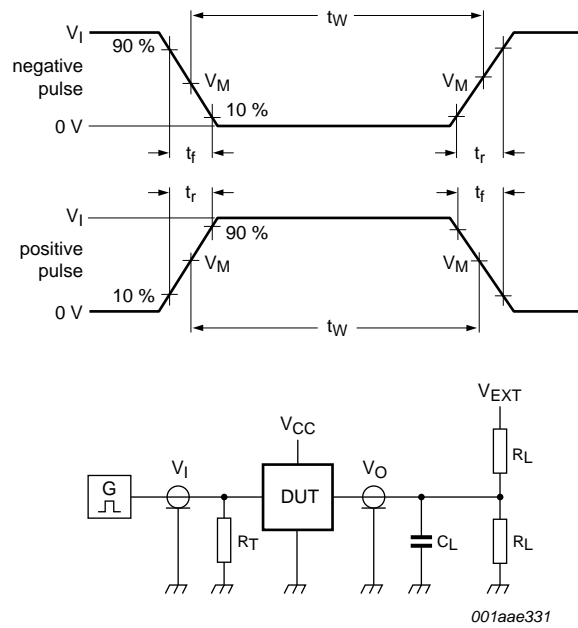


Table 8. Measurement points

| Supply voltage | Input | | Output | | |
|------------------|----------|---------------------|---------------------|---------------------------|---------------------------|
| V_{CC} | V_I | V_M | V_M | V_X | V_Y |
| 1.2 V | V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $V_{OL} + 0.15 \text{ V}$ | $V_{OH} - 0.15 \text{ V}$ |
| 1.65 V to 1.95 V | V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $V_{OL} + 0.15 \text{ V}$ | $V_{OH} - 0.15 \text{ V}$ |
| 2.3 V to 2.7 V | V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $V_{OL} + 0.15 \text{ V}$ | $V_{OH} - 0.15 \text{ V}$ |
| 2.7 V | 2.7 V | 1.5 V | 1.5 V | $V_{OL} + 0.3 \text{ V}$ | $V_{OH} - 0.3 \text{ V}$ |
| 3.0 V to 3.6 V | 2.7 V | 1.5 V | 1.5 V | $V_{OL} + 0.3 \text{ V}$ | $V_{OH} - 0.3 \text{ V}$ |



Test data is given in [Table 9](#). Definitions for test circuit:

R_L = Load resistance. C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 11. Test circuit for measuring switching times

Table 9. Test data

| Supply voltage | Input | | Load | | V_{EXT} | | |
|------------------|----------|---------------|-------|--------------|--------------------|--------------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PLH}, t_{PHL} | t_{PLZ}, t_{PZL} | t_{PHZ}, t_{PZH} |
| 1.2 V | V_{CC} | ≤ 2 ns | 30 pF | 1 k Ω | open | $2 \times V_{CC}$ | GND |
| 1.65 V to 1.95 V | V_{CC} | ≤ 2 ns | 30 pF | 1 k Ω | open | $2 \times V_{CC}$ | GND |
| 2.3 V to 2.7 V | V_{CC} | ≤ 2 ns | 30 pF | 500 Ω | open | $2 \times V_{CC}$ | GND |
| 2.7 V | 2.7 V | ≤ 2.5 ns | 50 pF | 500 Ω | open | $2 \times V_{CC}$ | GND |
| 3.0 V to 3.6 V | 2.7 V | ≤ 2.5 ns | 50 pF | 500 Ω | open | $2 \times V_{CC}$ | GND |

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

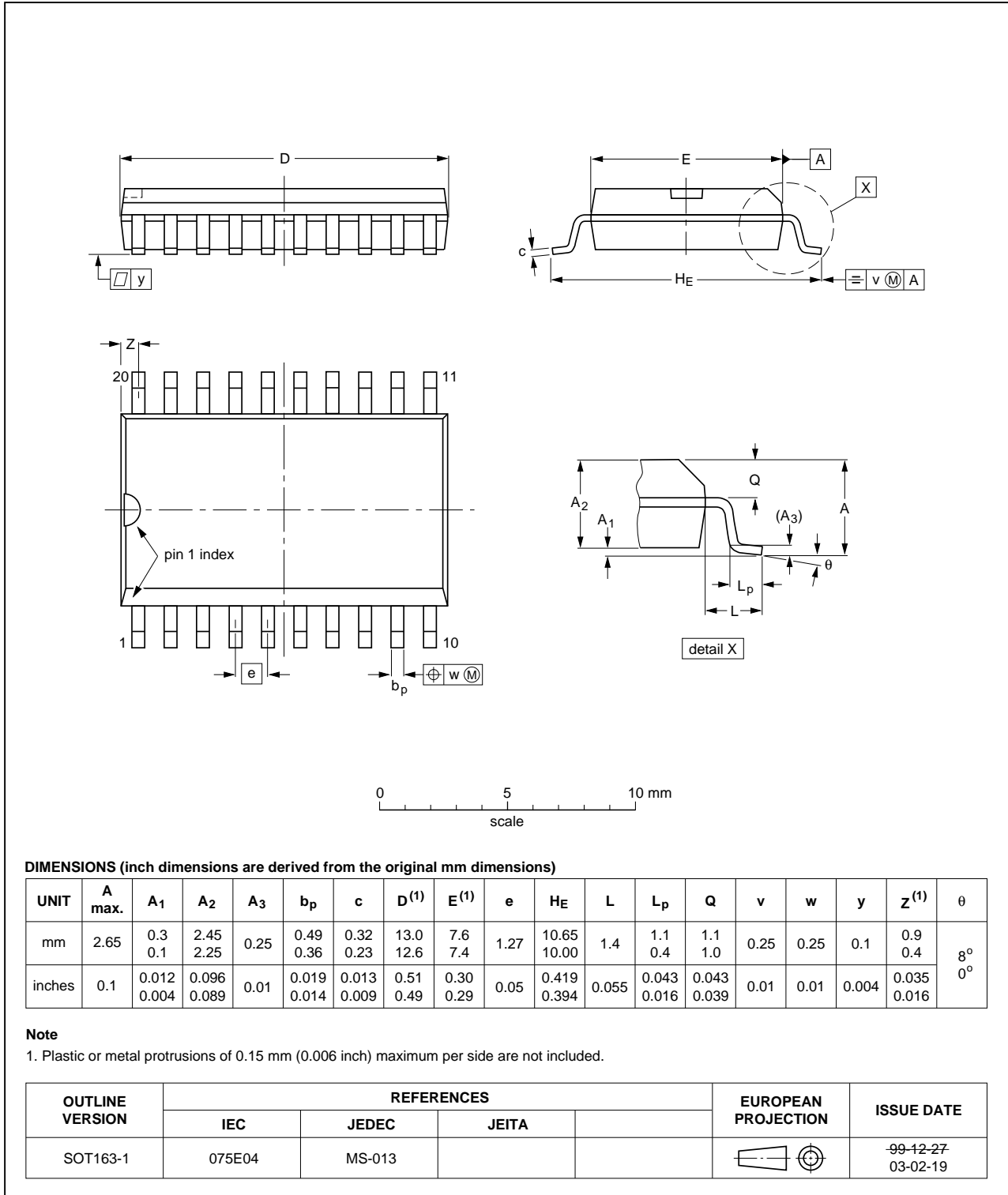


Fig 12. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

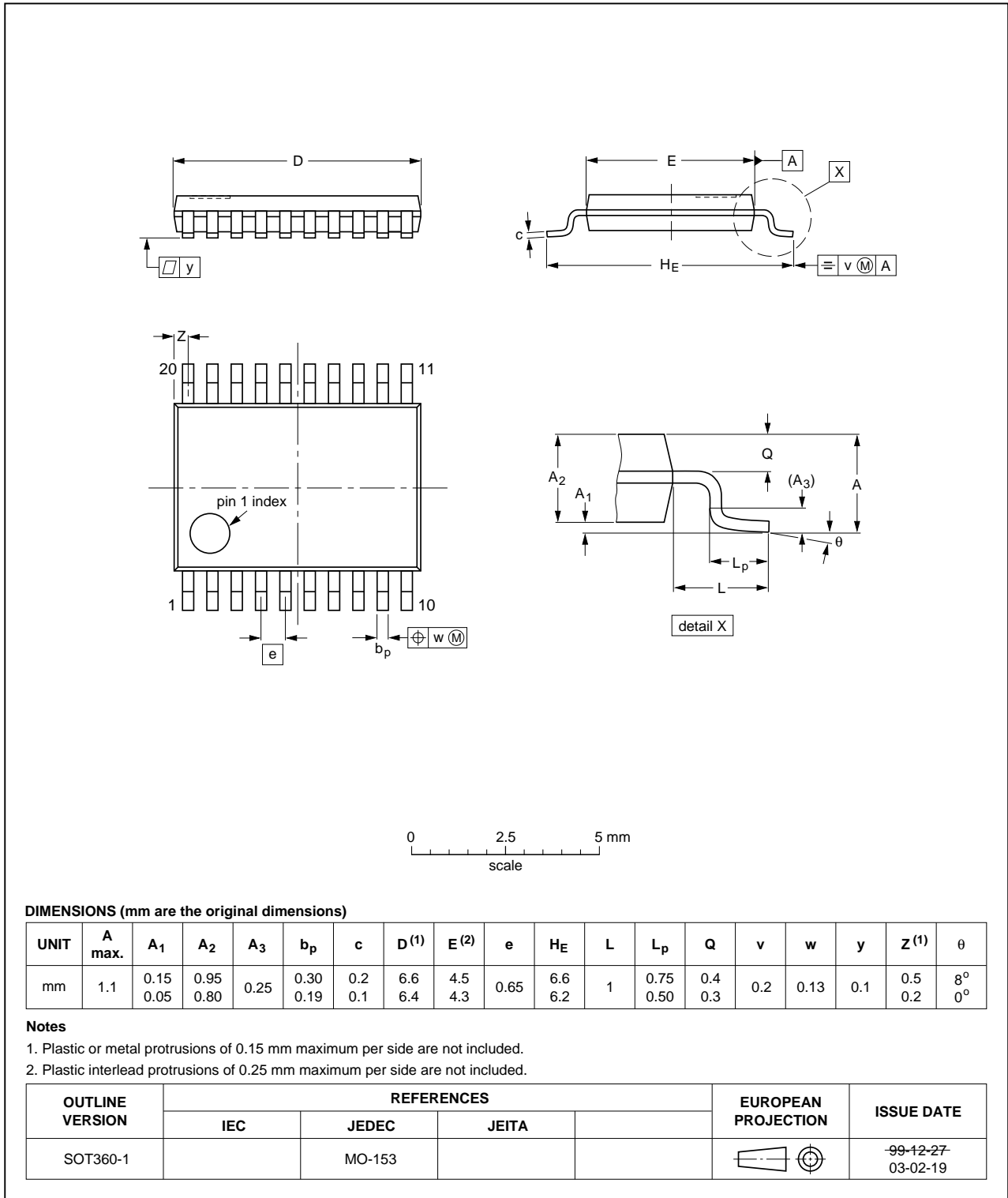


Fig 13. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

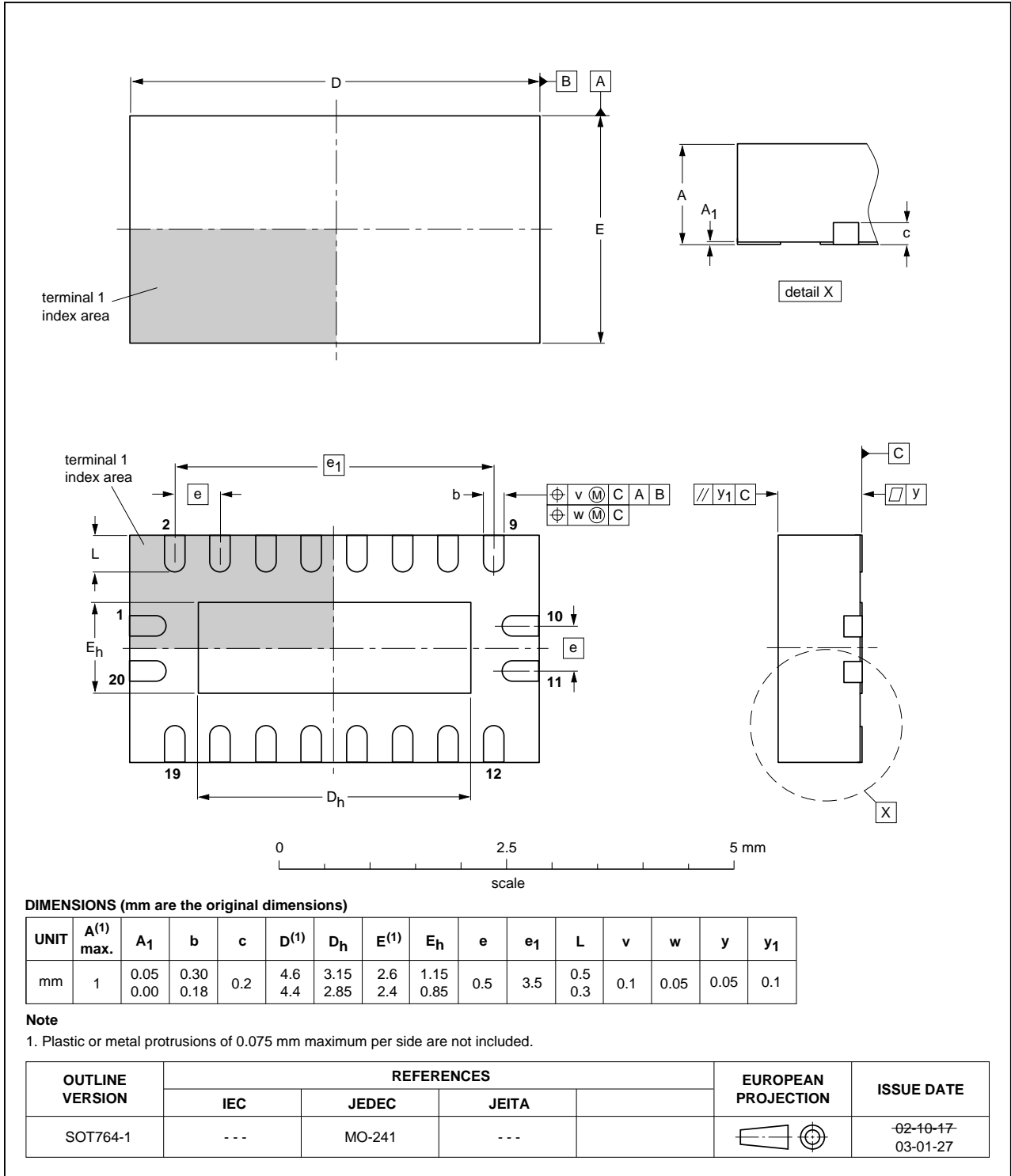


Fig 14. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|-----------------------------|
| CDM | Charged Device Model |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MIL | Military |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--------------------|--------------|--------------------|---------------|------------|
| 74LVC573A_Q100 v.1 | 20130129 | Product data sheet | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

15.2 Definitions

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